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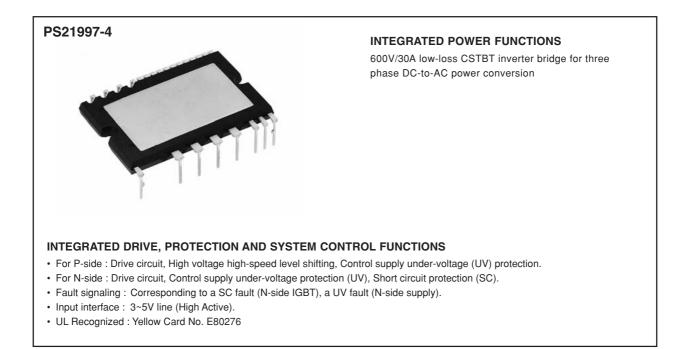
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MITSUBISHI SEMICONDUCTOR < Dual-In-Line Package Intelligent Power Module>

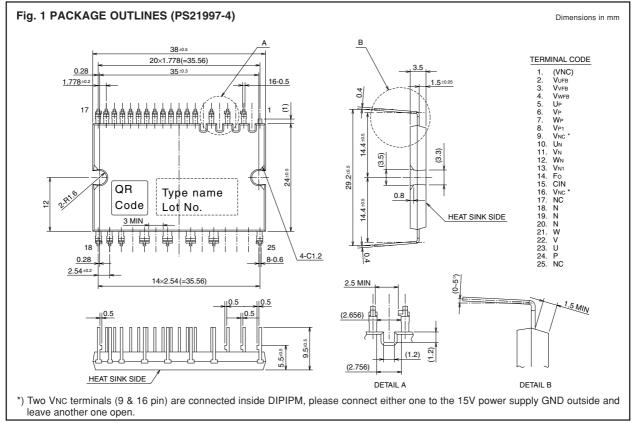
PS21997-4/-4A/-4C/-4W

TRANSFER-MOLD TYPE INSULATED TYPE



APPLICATION

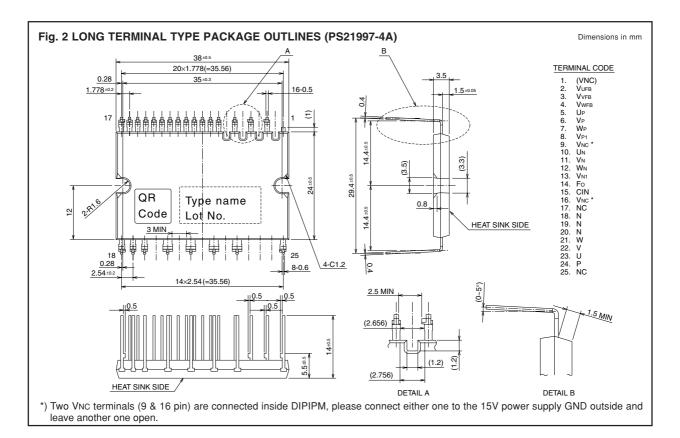
AC100V~200V three-phase inverter drive for small power motor control.

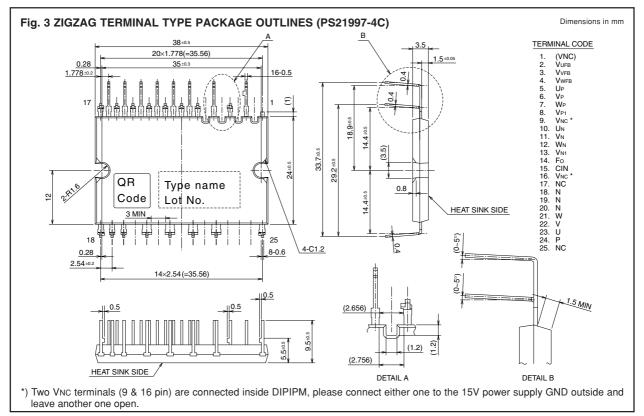


Note : CSTBT is registered trademark of MITSUBISHI ELECTRIC CORPORATION in Japan.



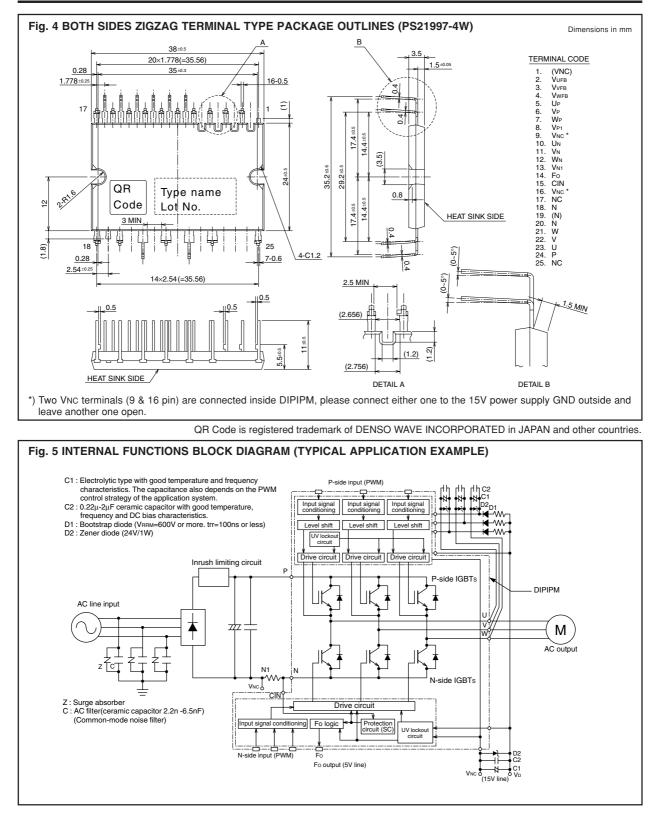
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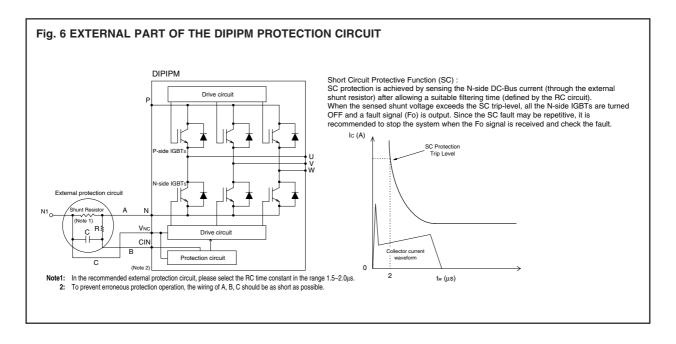


TRANSFER-MOLD TYPE INSULATED TYPE





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MAXIMUM RATINGS ($T_j = 25^{\circ}C$, unless otherwise noted) **INVERTER PART**

Symbol	Parameter	Condition		Ratings	Unit
Vcc	Supply voltage	Applied between P-N		450	V
VCC(surge)	Supply voltage (surge)	Applied between P-N		500	V
VCES	Collector-emitter voltage			600	V
±IC	Each IGBT collector current	Tc = 25°C		30	A
±IСР	Each IGBT collector current (peak)	Tc = 25°C, less than 1ms		60	A
Pc	Collector dissipation	Tc = 25°C, per 1 chip		47.6	W
Tj	Junction temperature		(Note 1)	-20~+125	°C

Note 1: The maximum junction temperature rating of the power chips integrated within the DIPIPM is 150°C (@ $Tc \le 100$ °C). However, to ensure safe operation of the DIPIPM, the average junction temperature should be limited to $T_{j(ave)} \le 125$ °C (@ $Tc \le 100$ °C).

CONTROL (PROTECTION) PART

Symbol	Parameter	Condition	Ratings	Unit
Vd	Control supply voltage	Applied between VP1-VNC, VN1-VNC	20	V
Vdb	Control supply voltage	Applied between VUFB-U, VVFB-V, VWFB-W	20	V
VIN	Input voltage	Applied between UP, VP, WP, UN, VN, WN-VNC	-0.5~VD+0.5	V
Vfo	Fault output supply voltage	Applied between FO-VNC	-0.5~VD+0.5	V
IFO	Fault output current	Sink current at FO terminal	1	mA
Vsc	Current sensing input voltage	Applied between CIN-VNC	-0.5~VD+0.5	V

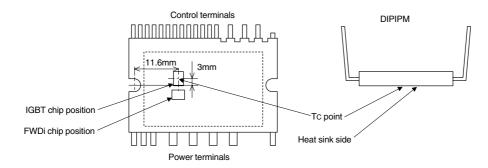


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TOTAL SYSTEM

Symbol	Parameter	Condition	Ratings	Unit
VCC(PROT)	Self protection supply voltage limit (short circuit protection capability)	$V_D = 13.5 \sim 16.5 V$, Inverter part T _j = 125°C, non-repetitive, less than 2µs	400	V
Тс	Module case operation temperature	(Note 2)	-20~+100	°C
Tstg	Storage temperature		-40~+125	°C
Viso	Isolation voltage	60Hz, Sinusoidal, 1 minute, Between pins and heat sink plate	1500	Vrms

Note 2: Tc measurement point



THERMAL RESISTANCE

Cumhal	Deverseter	Condition	Limits			Unit
Symbol Parameter		Condition	Min.	Тур.	Max.	Unit
Rth(j-c)Q	Junction to case thermal Inverter IGBT part (per 1/6 module)		—	—	2.1	°C/W
Rth(j-c)F	resistance (Note 3)	nce (Note 3) Inverter FWDi part (per 1/6 module)		—	3.0	°C/W

Note 3: Grease with good thermal conductivity and long-term quality should be applied evenly with +100µm~+200µm on the contacting surface of DIPIPM and heat sink.

The contacting thermal resistance between case and heat sink (Rth(c-f)) is determined by the thickness and the thermal conductivity of the applied grease.

For reference, Rth(c-f) (per 1/6 module) is about 0.3°C/W when the grease thickness is 20µm and the thermal conductivity is 1.0W/mK.

ELECTRICAL CHARACTERISTICS (Tj = 25°C, unless otherwise noted	d)
INVERTER PART	

Cumhal	Parameter	Condition		Limits			Unit	
Symbol	Parameter			Min.	Тур.	Max.	Unit	
	Collector-emitter saturation	VD = VDB = 15V	VD = VDB = 15V IC = 30A, Tj = 25°C		1.90	2.50	v	
VCE(sat) voltage		VIN = 5V	IC = 30A, Tj = 125°C	—	2.00	2.60	v	
VEC	FWDi forward voltage	$T_j = 25^{\circ}C, -IC = 30A, VIN = 0V$		—	1.70	2.20	V	
ton		Vcc = 300V, VD = VDB = 15V		0.70	1.30	1.90	μs	
trr				—	0.30	—	μs	
tc(on)	Switching times	IC = 30A, Tj = 125°C, VIN = $0 \leftrightarrow 5V$		—	0.40	0.60	μs	
toff		Inductive load (upper-lower arm)		—	1.70	2.65	μs	
tc(off)				—	0.40	1.00	μs	
ICES	ES Collector-emitter cut-off VCE = VCES		$T_j = 25^{\circ}C$	—	—	1	mA	
	current	VUE = VUES	Tj = 125°C	—	_	10	IIIA	



TRANSFER-MOLD TYPE INSULATED TYPE

CONTROL (PROTECTION) PART

Symbol	Parameter		Co	ndition		Limits	-	Unit
Symbol	Farameter		Condition			Тур.	Max.	Offic
		VD = VDB = 15V	Total of	of VP1-VNC, VN1-VNC	_	—	2.80	mA
ID	Circuit current	VIN = 5V	VUFB-	U, Vvfb-V, Vwfb-W	—	—	0.55	mA
		VD = VDB = 15V	Total of	of VP1-VNC, VN1-VNC	_	—	2.80	mA
		VIN = 0V	VUFB-	U, Vvfb-V, Vwfb-W	—	—	0.55	mA
VFOH	Fault output voltage	Vsc = 0V, Fo terminal pull-up to 5V by $10k\Omega$			4.9	—	—	V
VFOL	Fault output voltage	VSC = 1V, IFO = 1mA		—	—	0.95	V	
VSC(ref)	Short circuit trip level	VD = 15V (Note 4)		0.43	0.48	0.53	V	
lin	Input current	VIN = 5V		0.70	1.00	1.50	mA	
UVDBt			Trip level	Trip level	10.0	—	12.0	V
UVDBr	Control supply under-voltage	Ti≤ 125°C		Reset level	10.5	—	12.5	V
UVDt	protection	1] 2 125 0		Trip level	10.3	—	12.5	V
UVDr				Reset level	10.8	—	13.0	V
tFO	Fault output pulse width			(Note 5)	40	—	—	μs
Vth(on)	ON threshold voltage		· · · ·		_	2.1	2.6	V
Vth(off)	OFF threshold voltage	Applied between UP, VP, WP, UN, VN, WN-VNC		0.8	1.3	—	V	
Vth(hys)	ON/OFF threshold hysteresis voltage			0.35	0.65	_	V	

Note 4: Short circuit protection works only for the N-side. Please select the external shunt resistance such that the SC trip-level is up to 1.7 times of the current rating.

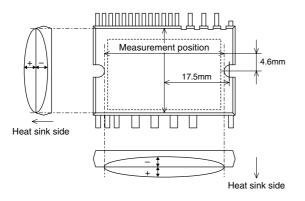
5: Fault signal is asserted only corresponding to a SC or a UV failure at N-side, and the Fo pulse width is different for each failure modes. For SC failure, Fo output is with a fixed width of 40μs(min), but for UV failure, Fo outputs continuously during the whole UV period, however, the minimum Fo pulse width is 40μs(min) for very short UV period less than 40μs.

MECHANICAL CHARACTERISTICS AND RATINGS

Devemeter	Condition			Linit		
Parameter			Min.	Тур.	Max.	Unit
Mounting torque	Mounting screw : M3 (Note 6) Recommended : 0.69 N·m		0.59	_	0.78	N∙m
Weight			—	10	—	g
Heat-sink flatness	(Note 7)		-50	—	100	μm

Note 6: Plain washers (ISO 7089~7094) are recommended.

Note 7: Flatness measurement position





TRANSFER-MOLD TYPE INSULATED TYPE

RECOMMENDED OPERATION CONDITIONS

Symbol Parameter		Condition		Limits			Unit
Symbol	Parameter	Condition		Min.	Тур.	Max.	
Vcc	Supply voltage	Applied between P-N		0	300	400	V
Vd	Control supply voltage	Applied between VP1-VNC, VN1-VNC		13.5	15.0	16.5	V
Vdb	Control supply voltage	Applied between VUFB-U, VVFB-V, VWFB-	W	13.0	15.0	18.5	V
$\Delta \text{VD}, \Delta \text{VDB}$	Control supply variation			-1	_	1	V/µs
tdead	Arm shoot-through blocking time	For each input signal, $TC \le 100^{\circ}C$			_	_	μs
fpwm	PWM input frequency	Tc ≤ 100°C, Tj ≤ 125°C			_	20	kHz
	VCC = 300V, VD = VDB = 15V,	fPWM = 5kHz	—	_	15.0		
lo	Allowable rms current	$P.F = 0.8$, sinusoidal PWM, $T_j \le 125^{\circ}C$, $Tc \le 100^{\circ}C$ (Note 8)	fpwm = 15kHz	_	_	10.0	Arms
PWIN(on)			(Note 9)	0.5	—	—	μs
	.	$200V \le Vcc \le 350V$, $13.5V \le VD \le 16.5V$,	Below rated current	1.5	_	_	
PWIN(off)	PWIN(off)Allowable minimum input pulse width $10.0V \le VD \le 10.0V$, $13.0V \le VDB \le 18.5V$, $-20^{\circ}C \le Tc \le 100^{\circ}C$, N-line wiring inductance less than 10nH (Note 10)		Between rated current and 1.7 times of rated current	3.0	_		μs
VNC	VNC variation	Between VNC-N (including surge)		-5.0	—	5.0	V

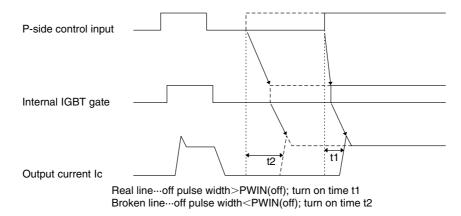
Note 8 : The allowable rms current value depends on the actual application conditions.

9 : Input signal with on pulse width less than PWIN(on) might make no response.

10: Input signal with off pulse width less than PWIN(off) might make no response, or make delayed response to P-side input only. (The delay is less than about 4µs.)

Please refer Fig.7 about delayed response and Fig.11 about N-line inductance.

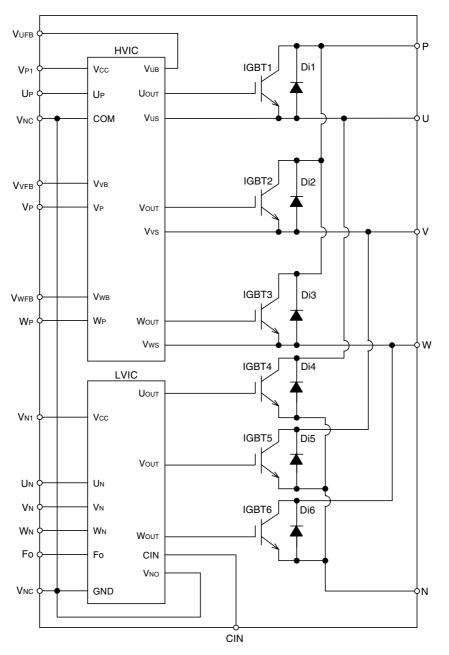
Fig. 7 About Delayed Response Against Shorter Input Off Signal Than PWIN(off) (P-side only)





TRANSFER-MOLD TYPE INSULATED TYPE

Fig. 8 THE DIPIPM INTERNAL CIRCUIT



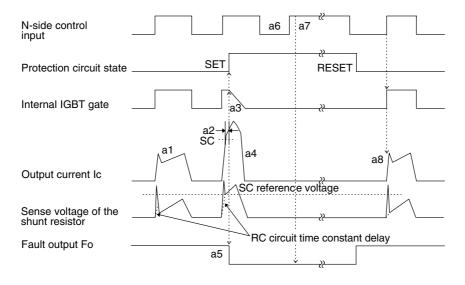


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Fig. 9 TIMING CHART OF THE PROTECTIVE FUNCTIONS

[A] Short-Circuit Protection (N-side only with the external shunt resistor and RC filter)

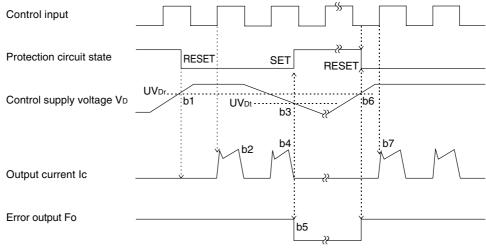
- a1. Normal operation : IGBT ON and carrying current.
- a2. Short circuit is detected (SC trigger).
- a3. All N-side IGBTs' gates are hard interrupted.
- a4. All N-side IGBTs turn OFF.
- a5. Fo is output (tFO(min) = 40μ s).
- a6. Input "L".
- a7. Input "H". But IGBT is still OFF state during outputting Fo.
- a8. IGBT turns ON when L \rightarrow H signal is input after Fo is reset.



[B] Under-Voltage Protection (N-side, UVD)

- b1. Control supply voltage VD rises : After VD level rises over under voltage reset level (UVDr), the circuits start to operate when next input is applied.

- b2. Normal operation : IGBT ON and carrying current. b3. VD level dips to under voltage trip level. (UVDt). b4. All N-side IGBTs turn OFF in spite of control input condition. b5. F0 is output. (tF0 \ge 40µs and F0 outputs continuously during UV period).
- b6. VD level rises over UVDr
- b7. Normal operation : IGBT ON and carrying current.

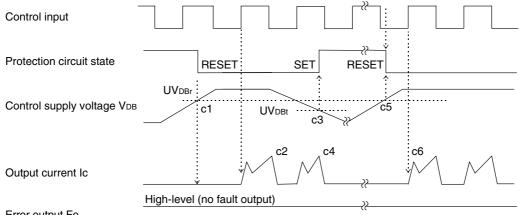




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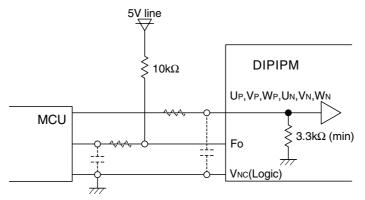
[C] Under-Voltage Protection (P-side, UVDB)

- c1. Control supply voltage VDB rises : After VDB level rises over under voltage reset level (UVDBr), the circuits start to operate when next input is applied.
- c2. Normal operation : IGBT ON and carrying current.
- c3. VDB level dips to under voltage trip level. (UVDBt).
- c4. P-side IGBT turns OFF in spite of control input signal level, but there is no Fo signal output.
- c5. VDB level rises over UVDBr.
- c6. Normal operation : IGBT ON and carrying current.



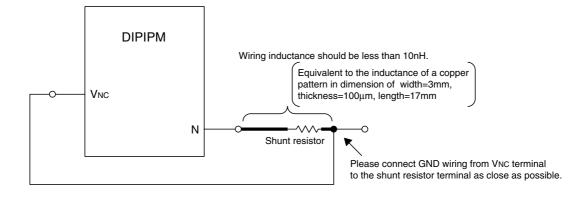
Error output Fo

Fig. 10 AN INSTANCE OF INTERFACE CIRCUIT



Note : The setting of RC coupling at each input (parts shown dotted) depends on the PWM control scheme and the wiring impedance of the printed circuit board.
 Input circuit integrates a 3.3kΩ (min) pull-down resistor. Therefore, when using an external filtering resistor, pay attention to the turn-on threshold voltage.

Fig. 11 WIRING CONNECTION OF SHUNT RESISTOR





TRANSFER-MOLD TYPE INSULATED TYPE

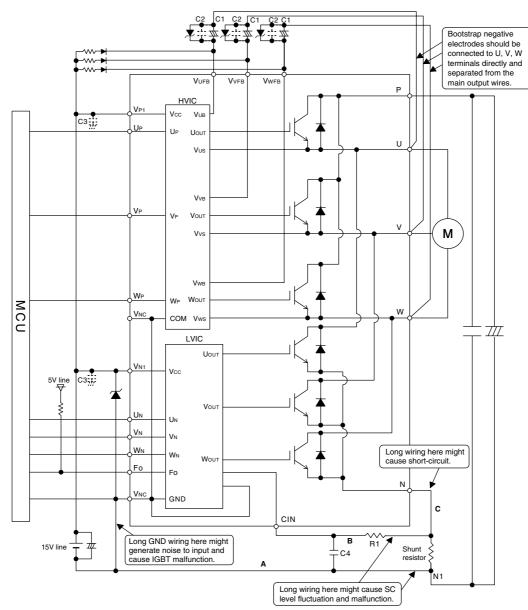


Fig. 12 AN EXAMPLE OF TYPICAL DIPIPM APPLICATION CIRCUIT

- Note 1 : Input drive is High-active type. There is a 3.3kΩ (Min.) pull-down resistor in the input circuit of IC. To prevent malfunction, the wiring of each input should be as short as possible. When using RC coupling circuit, make sure the input signal level meet the turn-on and turn-off threshold voltage.
 - 2 : Thanks to HVIC inside the module, direct coupling to MCU without any opto-coupler or transformer isolation is possible.
 - 3 : Fo output is open drain type. It should be pulled up to the MCU or control power supply (e.g. 5V, 15V) by a resistor that makes IFo up to 1mA.
 - 4 : To prevent erroneous protection, the wiring of A, B, C should be as short as possible.
 - 5 The time constant R1C4 of the protection circuit should be selected in the range of 1.5-2µs. SC interrupting time might vary with the wiring pattern. Tight tolerance, temp-compensated type is recommended for R1, C4
 - 6 : All capacitors should be mounted as close to the terminals of DIPIPM as possible. (C1: good temperature, frequency characteristic electrolytic type, and C2, C3 (0.22~2µF) : good temperature, frequency and DC bias characteristic ceramic type are recommended.)
 - 7 : To prevent surge destruction, the wiring between the smoothing capacitor and the P, N1 terminals should be as short as possible.
 Generally a 0.1-0.22µF snubber between the P-N1 terminals is recommended.
 - 8 : Two VNC terminals (9 & 16 pin) are connected inside DIPIPM, please connect either one to the 15V power supply GND and leave the other open.
 - 9 : It is recommended to insert a Zener diode (24V/1W) between each pair of control supply terminals to prevent surge destruction.
 - 10 : If control GND is connected with power GND by common broad pattern, it may cause malfunction by power GND fluctuation. It is recommended to connect control GND and power GND at only a point N1.
 - 11 : High voltage (VRRM =600V or more) and fast recovery type (tr=100ns or less) diodes should be used in the bootstrap circuit.

